SOT2277-1

WLCSP123, wafer level chip-size package, 123 terminals, 0.4 mm pitch, 4.95 mm x 4.395 mm x 0.525 mm body

25 August 2025 **Package information**

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP123
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	S (silicon)
Mounting method type	S (surface mount)
Issue date	05-03-2025
Manufacturer package code	98ASA02243D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	4.95	-	mm
package width	-	4.395	-	mm
seated height	-	0.525	0.565	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	123	-	

2 Package outline

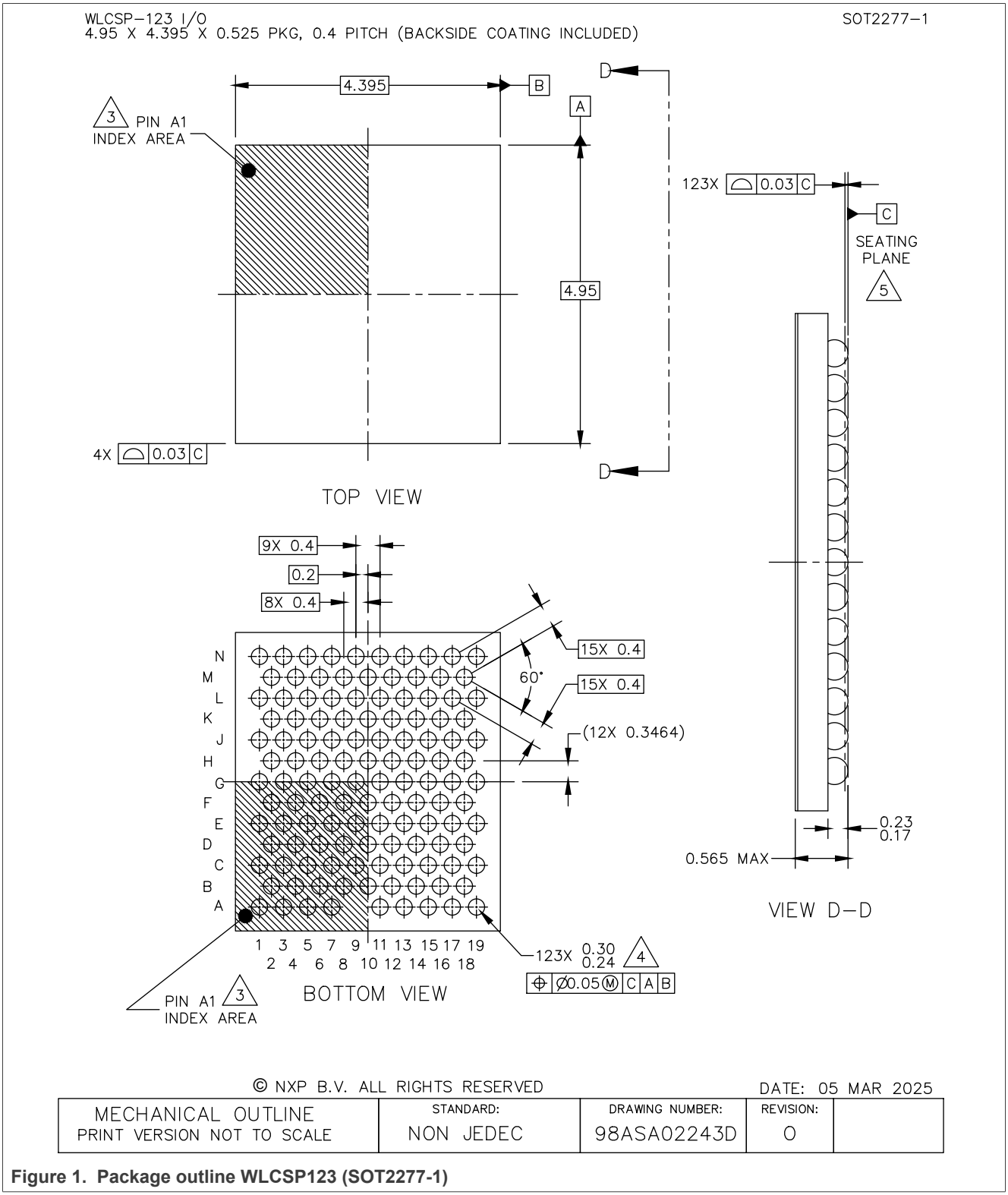

Figure 1. Package outline WLCSP123 (SOT2277-1)

3 Soldering

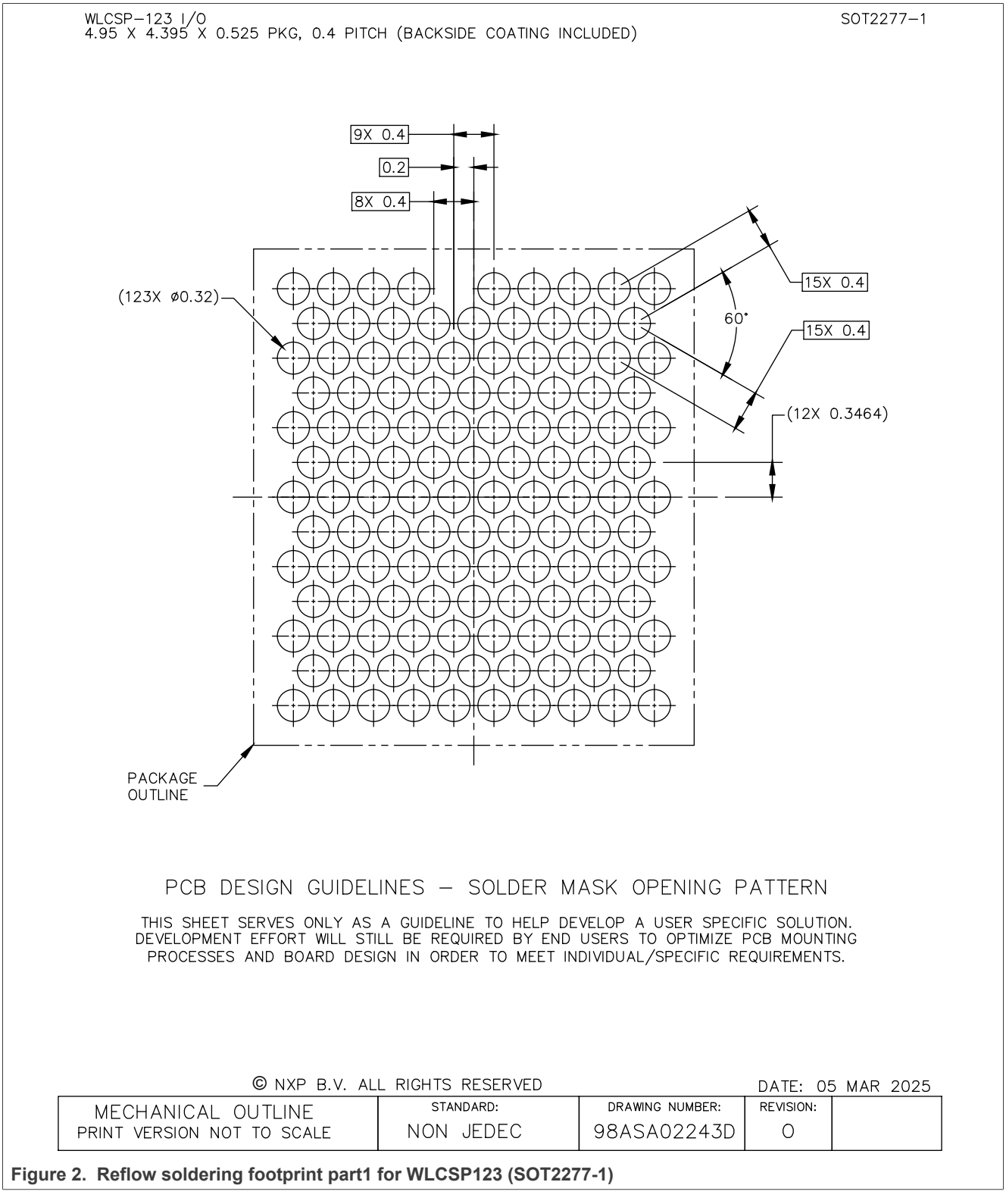

Figure 2. Reflow soldering footprint part1 for WLCSP123 (SOT2277-1)

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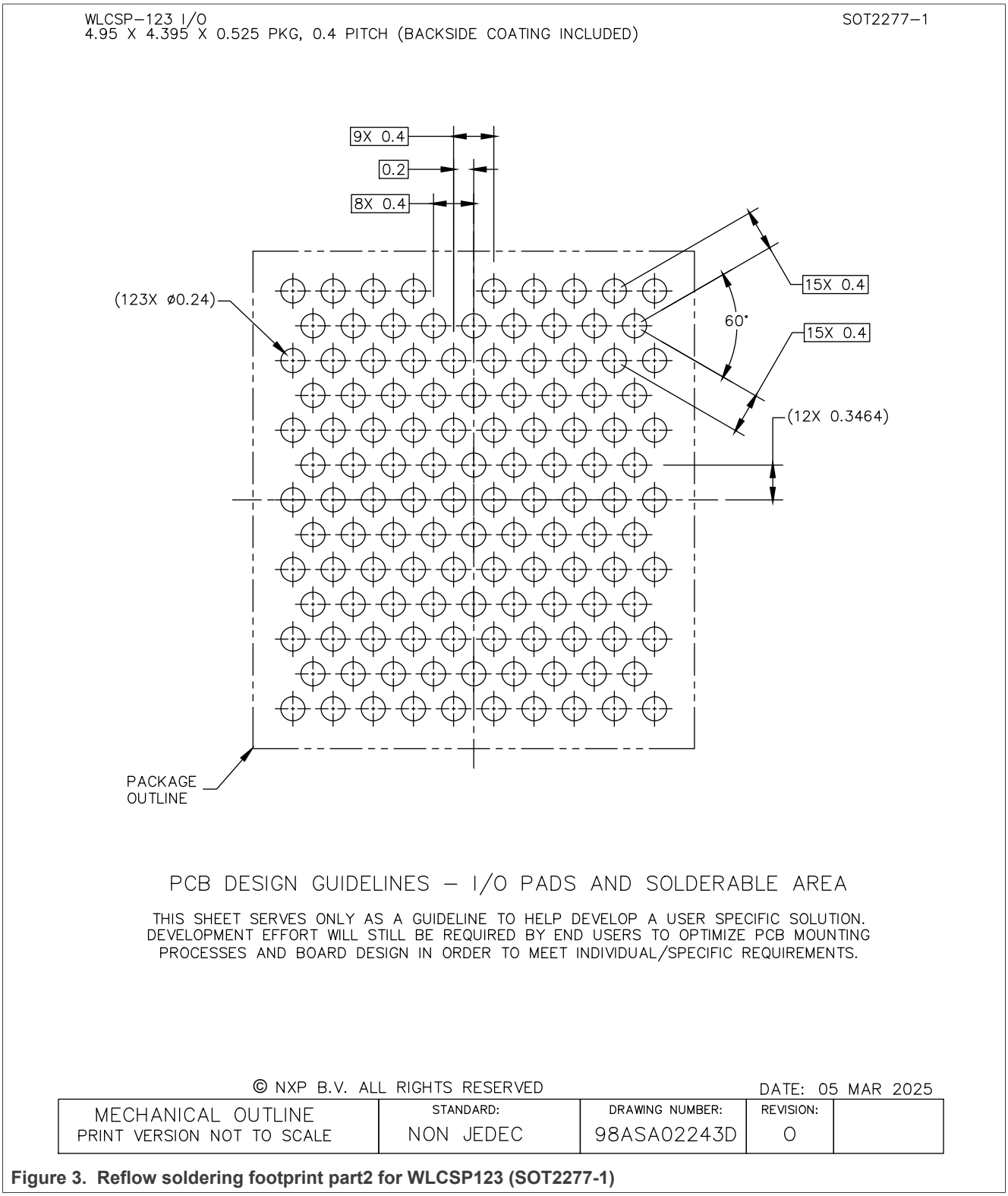

Figure 3. Reflow soldering footprint part2 for WLCSP123 (SOT2277-1)

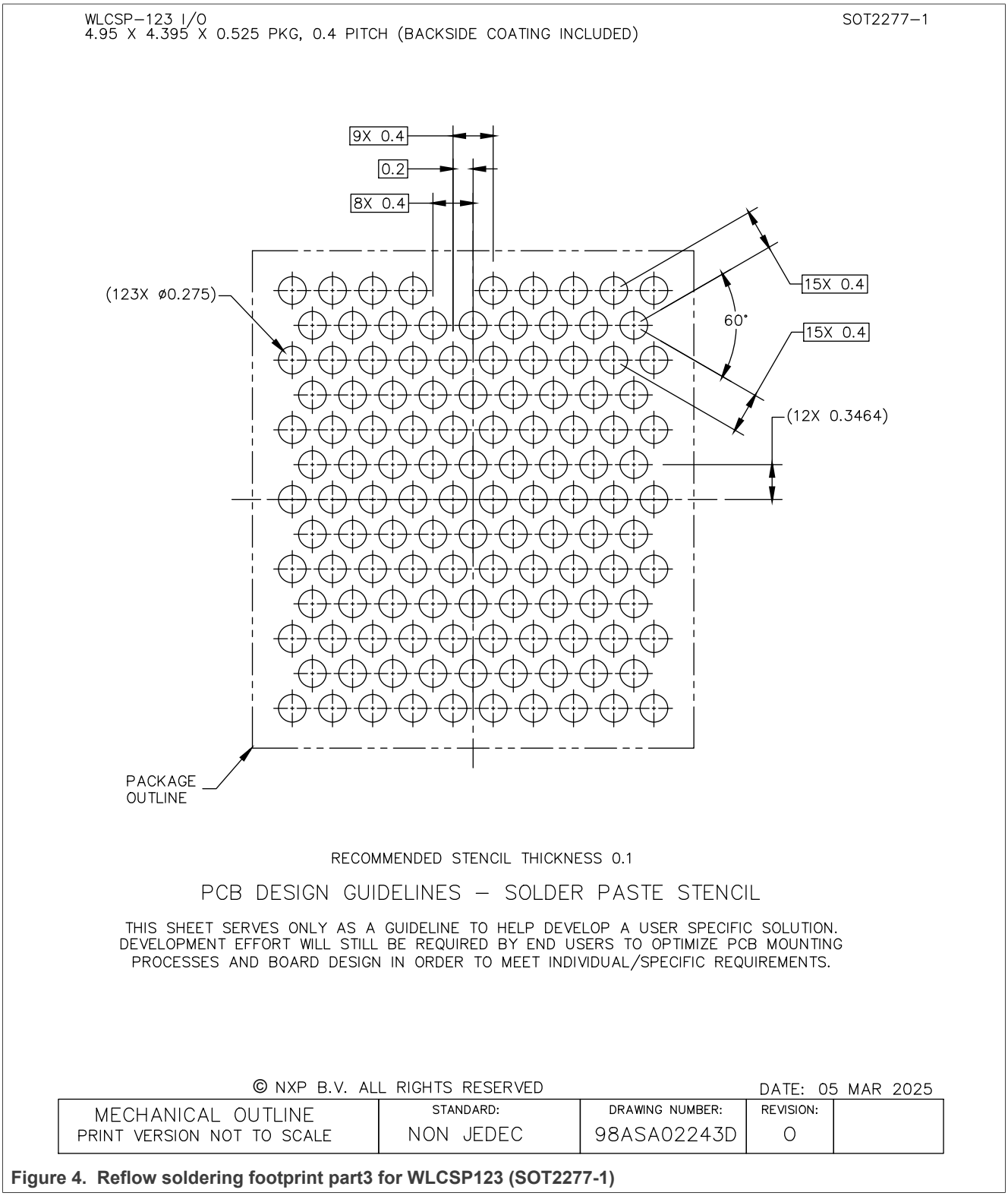

Figure 4. Reflow soldering footprint part3 for WLCSP123 (SOT2277-1)

WLCSP123, wafer level chip-size package, 123 terminals, 0.4 mm pitch, 4.95 mm x 4.395 mm x 0.525 mm body

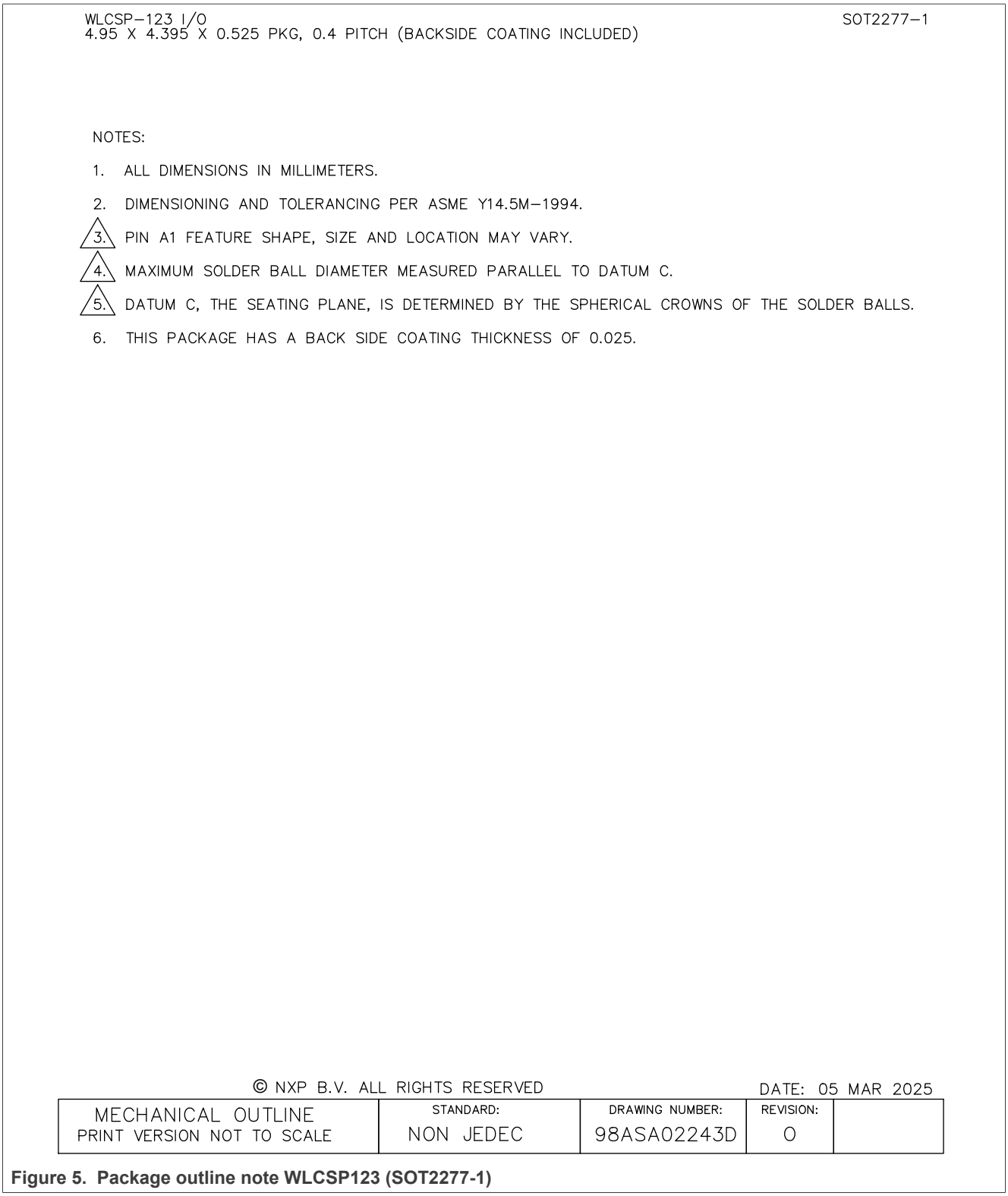

Figure 5. Package outline note WLCSP123 (SOT2277-1)

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Contents